

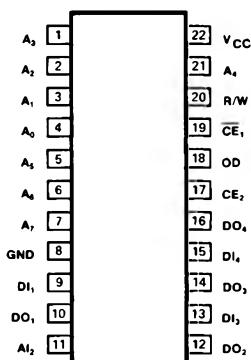
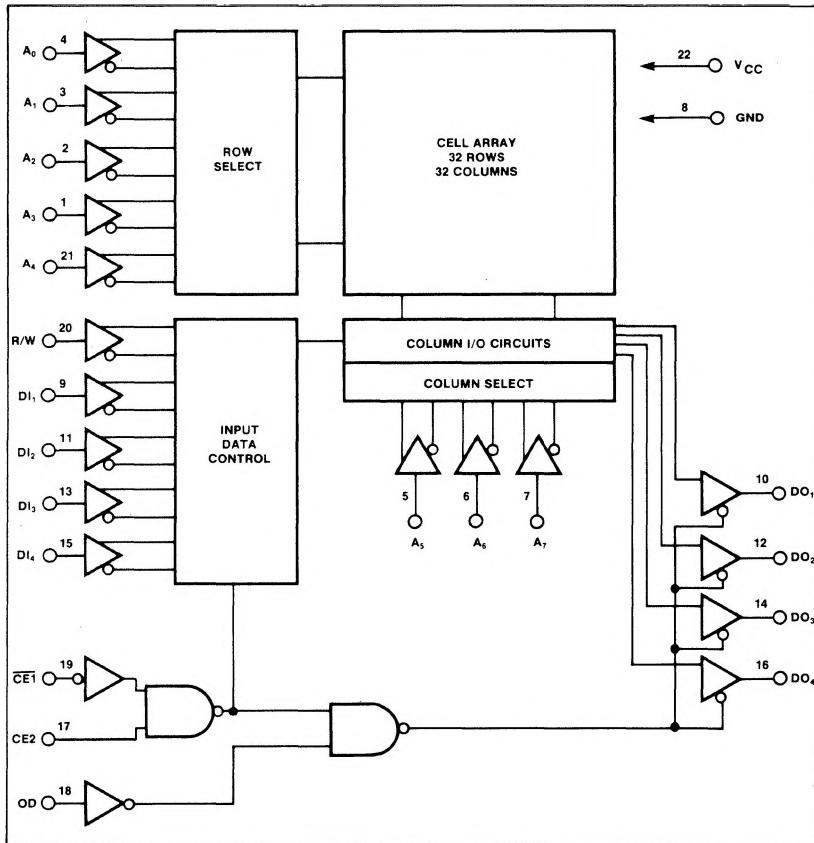
DESCRIPTION

The 2101 series is high performance, low power static read/write RAM's.

The 2101 series is fabricated with n-channel silicon gate technology which allows the design of high performance easy to use MOS circuits and provides a high functional density on a given monolithic chip.

FEATURES

- Fully static
- No refresh operations, sense amps or clocks required
- All inputs and outputs are TTL compatible
- One 5V power supply required

PIN CONFIGURATION**F,N PACKAGE****BLOCK DIAGRAM****ABSOLUTE MAXIMUM RATINGS¹**

PARAMETER	RATING	UNIT
T _A	Temperature range Operating under bias	°C
T _{TSG}	Storage	
P _D	Power dissipation	W
	Voltage on any pin with respect to ground	V

DC ELECTRICAL CHARACTERISTICS TA = 0°C to 70°C, VCC = 5V ± 5%, unless otherwise specified

PARAMETER	TEST CONDITIONS	LIMITS			UNIT
		Min	Typ ²	Max	
V _{IL} V _{IH}	Input voltage Low High	-0.5 2.2		0.65 V _{CC}	V
V _{OL} V _{OH}	Output voltage Low High	I _{OL} = 2.0mA I _{OH} = 150μA	2.2	0.45	V
I _{LI}	Input current	V _{IN} = 0 to 5.25V		10	μA
I _{LOH} I _{LOL}	I/O leakage current ³	CE ₁ = 2.2V V _{OUT} = 4.0V V _{OUT} = 0.45V		15 -50	μA
I _{CC1} I _{CC2}	Supply current	V _{IN} = 5.25V, I _O = 0mA TA = 25°C TA = 0°C	30	60 70	mA
C _{IN} C _{OUT}	Capacitance ³ Input (All pins) Output	V _{IN} = 0V V _{OUT} = 0V	4 8	8 12	pF

AC ELECTRICAL CHARACTERISTICS TA = 0°C to 70°C, V_{CC} = 5V ± 5%, Input pulse levels = +0.65V to 2.2V, Input pulse rise and fall times = 20ns, Timing measurement reference level = 1.5V, Output load = 1 TTL gate and C_L = 100pF, unless otherwise specified.

PARAMETER	TO	FROM	2101			2101-1			2101-2			UNIT
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
t _{RC} t _A t _{CO} t _{DOD} t _{DIF} t _{OH}	READ CYCLE Read cycle Access time	Output Output High Z state	1,000		500	1,000	500	650	650	650	650	ns ns ns ns ns ns
		Chip enable Output disable Data output		800 700 200	0 40	350 300 150		0 40	350 300 150		400 350 150	ns ns ns
	Previous read data valid after change of address											
t _{WC} t _{AW} t _{CW}	WRITE CYCLE Write cycle Write delay	Write	1,000 150 900		500 100 400			650 150 550				ns ns ns
t _{DW} t _{DH}	Setup and hold time Setup time Hold time	Rise of R/W Change of data in Output	Data in Rise of R/W	700 100		280 100			400 100			ns
t _{DS}	Setup time	Output disable	200		150			150				
t _{WP} t _{WR}	Write pulse Write recovery			750 50		300 50			400 50			ns ns

NOTES

- Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or at any other condition above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
- Typical values are for TA = 25°C and typical supply voltage.
- This parameter is periodically sampled and is not 100% tested.
- t_{OF} is with respect to the trailing edge of CE₁, CE₂ or OD, whichever occurs first.
- CD should be tied low for separate I/O operation.

TIMING DIAGRAMS

